

New Orleans, LA, USA - 25 May 2017

Name	Employer	Affiliation
Agnes, Andrea	STMicroelectronics	STMicroelectronics
Anslow, Peter	Ciena Corporation	Ciena Corporation
Beruto, Piergiorgio		Canova Tech Srl
Brandt, David	Rockwell Automation	Rockwell Automation
Braun, Ralf-Peter	Deutsche Telekom AG	Deutsche Telekom AG
Brillhart, Theodore	Fluke Corporation	Fluke Corporation
Brooks, Paul	Viavi solutions GmbH	Viavi Solutions
Brown, Alan M	ADTRAN Inc.	ADTRAN Inc.
Brown, Matthew	Applied Micro (AMCC)	Applied Micro (AMCC)
Brownlee, Phillip	TDK Corporation	TDK Corporation
Burrell, Gary	Elenion Technologies	Elenion Technologies
Butter, Adrian	GLOBALFOUNDRIES	GLOBALFOUNDRIES
Carlson, Steven	High-Speed Design Inc.	Robert Bosch GmbH
Chen, Chan	Applied Optoelectronics, Inc.	Applied Optoelectronics, Inc.
Choudhury, Golam	OFS	OFS
D'Ambrosia, John	Futurewei Technologies	Futurewei (Subsidiary of Huawei)
Dawe, Piers J G	Mellanox Technologies	Mellanox Technologies
Dawson, Fred	Chemours Canada Company	Chemours Canada Company
Donahue, Curtis	University of New Hampshire	UNH-IOL
Dudek, Michael	Cavium	Cavium
Eitel, Cornelia	Hirschmann Automation and Control, Inc.	Hirschmann Automation and Control, Inc.
Estes, David	Spirent Communications	Spirent Communications
Ewen, John	GLOBALFOUNDRIES	GLOBALFOUNDRIES
Flatman, Alan	LAN Technologies Corporation,	LAN Technologies Corporation,
Franchuk, Brian	Emerson Process Management	Emerson Process Management
Fritsche, Matthias	HARTING Technologie Gruppe	HARTING Electronics GmbH
Goergen, Joel	Cisco Systems, Inc.	Cisco Systems, Inc.
Goldberg, Jonathan	IEEE Standards Association (IEEE-	IEEE STAFF
Graber, Steffen	Pepperl+Fuchs GmbH	Pepperl+Fuchs GmbH
Grow, Robert	RMG Consulting	RMG Consulting
GUO, YONG	ZTE Corporation	ZTE Corporation
Gustlin, Mark	Xilinx	Xilinx
Hajduczenia, Marek	Charter Communications	Charter Communications
Hayakawa, Akinori	FUJITSU LABORATORIES LIMITED	FUJITSU LABORATORIES LIMITED
Healey, Adam	Broadcom Ltd.	Broadcom Ltd.
Herbst, Thomas	Silver Spring Networks Inc.	Herbst LLC
Hess, David	CORD DATA	CORD DATA
Hidaka, Yasuo	Fujitsu Laboratories of America,	Fujitsu Laboratories of America,
Hormmeyer, Bernd	Phoenix Contact	Phoenix Contact
HYAKUTAKE, YASUHIRO	Adamant Co., Ltd.	Adamant Co., Ltd.
Ingham, Jonathan	Foxconn Interconnect Technology	Foxconn Interconnect Technology

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Isono, Hideki	FUJITSU	Fujitsu Optical Components
Jackson, Kenneth	Sumitomo Electric Device	Sumitomo Electric Industries, LTD
Jones, Chad	Cisco Systems, Inc.	Cisco Systems, Inc.
Jones, Peter	Cisco Systems, Inc.	Cisco Systems, Inc.
Kareti, Upen	Cisco Systems, Inc.	Cisco Systems, Inc.
Kimber, Eric	Semtech Ltd	Semtech Ltd
Klempa, Michael	University of New Hampshire	University of New Hampshire
Kolesar, Paul	CommScope	CommScope, Inc.
Lapak, Jeffrey	University of New Hampshire	University of New Hampshire
Laubach, Mark	Broadcom Limited	Broadcom Corporation
Law, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Lewis, David	Lumentum Inc.	Lumentum Inc.
Lewis, Jon	Dell	Dell
Maki, Jeffery	Juniper Networks, Inc.	Juniper Networks, Inc.
Malicoat, David	Malicoat Networking Solutions	SENKO Advanced Components
McCarthy, Mick	Analog Devices Inc.	Analog Devices Inc.
Mcdermott, Thomas	FUJITSU	FUJITSU
McSorley, Gregory	Amphenol Corporation	Amphenol Corporation
Mellitz, Richard	Samtec, Inc.	Samtec, Inc.
Moffitt, Bryan	CommScope	CommScope, Inc.
Nowell, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
Ofelt, David	Juniper Networks, Inc.	Juniper Networks, Inc.
Palkert, Thomas	EIC	Molex-MoSys
Rabinovich, Rick	Ixia	Ixia
Remein, Duane	Futurewei Technologies	Huawei Technologies Co. Ltd
Rotolo, Salvatore	STMicroelectronics	STMicroelectronics
Sambasivan, Sam	AT&T	AT&T
Sayre, Edward	Teraspeed Consulting, a division	Teraspeed, a division of Samtec
Schweitz, Laura	Turck Inc.	Turck Inc.
Shariff, Masood	CommScope, Inc.	CommScope, Inc.
Smith, Daniel	Seagate Technology LLC	Seagate Technology LLC
Sommers, Scott	Molex Incorporated	Molex Incorporated
Sparrowhawk, Bryan	Leviton Manufacturing Co.	Leviton Manufacturing Co.
Sprague, Edward	Infinera Corporation	Infinera Corporation
Stassar, Peter	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd
Stewart, Heath	Linear Technology	Linear Technology
Stover, David	Linear Technology	Linear Technology
Taylor, Bharat	Semtech Canada Corporation	Semtech Canada Corporation
TAKAHARA, TOMOO	Fujitsu Optical Components Limited	FUJITSU LABORATORIES LIMITED
Tamura, Kohichi	Oclaro Japan Inc.	Oclaro Japan Inc.
Thompson, Geoffrey	GraCaSI S.A.	INDEPENDENT
Tracy, Nathan	TE Connectivity	TE Connectivity

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Traverso, Matthew	Cisco Systems, Inc.	Cisco Systems, Inc.
Trowbridge, Stephen	Nokia	Nokia
Umnov, Alexander	Corning Incorporated	Corning Incorporated
Vanderlaan, Paul	Berk-Tek LLC	Berk-Tek LLC
Wendt, Matthias	Philips Lighting	Philips Lighting
Wertheim, Oded	Mellanox Technologies	Mellanox Technologies
Winkel, Ludwig	Siemens AG	Siemens AG
Young, Adrian	Leviton Manufacturing Co.	Leviton Manufacturing Co.
Young, James		CommScope
Zhang, Junwen	ZTE TX Inc	ZTE TX Inc
Zhong, Qiwen	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Zhuang, Yan	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd
Zielinski, Martin	Emerson Electric Co.	Emerson Process Management
Zimmerman, George	CME Consulting	ADI, Aquantia, CommScope, Inc.,
Zivny, Pavel	Tektronix, Inc.	Tektronix, Inc.